

REMARKS

I. Formalities

Claims 27-46 remain in the subject patent application. No claims are amended, canceled, or added. Accordingly, Applicants respectfully submit that no new matter is added herein.

II. Response to the 35 U.S.C. §103 Rejections

Claims 42-46 were rejected under 35 U.S.C. §103(a) as allegedly being unpatentable over U.S. Patent No. 6,133,637 to Hikita et al. (hereinafter “Hikita”) in view of U.S. Patent No. 6,507,120 to Lo et al. (hereinafter “Lo”). These rejections are respectfully traversed in view of the remarks made below.

A. Remarks Directed to Claim 42

Claim 42 is directed to a method of manufacturing a semiconductor component that requires, among other steps, the steps of: (1) providing a semiconductor chip having an active side and an inactive side; (2) attaching to the semiconductor chip an integrated passive component that comprises a passive device; and (3) attaching the semiconductor chip to the leadframe such that the active side of the chip faces the leadframe and the inactive side of the chip faces the integrated passive component. The Office Action asserts that Hikita discloses steps (1) and (2), and that Lo discloses step (3).

Despite the assertion of the Office Action, it is respectfully submitted that Hikita fails to teach or suggest step (2) and that Lo fails to teach or suggest step (3). More specifically, Applicants respectfully submit that neither Hikita nor Lo discloses an integrated passive component attached to a semiconductor chip, and that, therefore, Hikita fails to teach or suggest the step of attaching an integrated passive component to a semiconductor chip, and Lo fails to teach or suggest attaching a semiconductor chip to a leadframe such that the inactive side of the chip faces an integrated passive component.

The Office Action asserts that element 14 of Hikita’s FIG. 39 is an integrated passive component. Element 14, however, is a semiconductor chip (see, e.g., column 19, line 37 of

Hikita). It is respectfully submitted that a semiconductor chip, while it may contain a passive component, is not itself a passive component. Moreover, Hikita does not teach or suggest an integrated passive component anywhere within the semiconductor device 10 of FIG. 39. Because it does not teach or suggest an integrated passive component, Applicants respectfully submit that Hikita fails to teach or suggest step (2) of claim 42.

Lo discloses a flip chip type quad flat non-leaded package containing a die having an active surface and a backside (see Abstract) but, as stated above, it does not teach or suggest an integrated passive component within that package. Element 230 from FIGs. 7 and 11, element 238 from FIGs. 8 and 12, and element 242 from FIGs. 9-12 appear to be the only components of the package of Lo other than die 210, solder bumps 218, and leads 202, and each of elements 230, 238, and 242 are heat sinks. It is respectfully submitted that a heat sink is not an integrated passive component.

Based on the foregoing, Applicants respectfully submit that the rejection of claim 42 should be withdrawn. Such withdrawal of the rejections is respectfully requested.

B. Remarks Directed to Claims 43-46

Dependent claims must be construed to include all of the limitations of the claims from which they depend, as required by 37 C.F.R. 1.75(c) and M.P.E.P. 608.01(n). Therefore, claims 43-46, which depend from claim 42, are also not taught or suggested by Hikita or Lo, or their combination, for at least the same reasons as listed earlier for claim 42. Accordingly, Applicants respectfully request that the rejections of claims 43-46 be withdrawn.

III. Remarks Directed to the Allowable Subject Matter

The allowance of claims 27-41 is noted with approval and thanks. Applicants note that the body of the Office Action lists the allowed claims as claims 28-41, but that the summary sheet for the Office Action lists the allowed claims as claims 27-41. Because the Office does not reject claim 27 and does not respond to Applicants' arguments in favor of patentability for claim

27 that were submitted in the response filed on June 27, 2005, and also because of the indication in the Office Action Summary of the allowance of claim 27, Applicants assume that claim 27 has indeed been allowed along with claims 28-41.

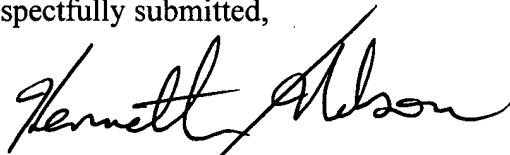
CONCLUSION

Applicants have made an earnest attempt to place this case in condition for allowance. In light of the remarks set forth above, Applicants respectfully request reconsideration and allowance of all of the pending claims.

No fees are believed to be due in connection with this paper. However, the Commissioner for Patents is hereby authorized to charge any fees necessitated by this Response, or credit any overpayment, to Account No. 02-4467.

If there are matters that can be discussed by telephone to further the prosecution of this application, Applicants invite Examiner Vu to call the undersigned attorney at the Examiner's convenience.

Respectfully submitted,

A handwritten signature in black ink, appearing to read "Kenneth A. Nelson", written over a horizontal line.

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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

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